- Three Differential Transceivers in One Package
- Signaling Rates[†] Up to 30 Mbps
- Low Power and High Speed
- Designed for TIA/EIA-485, TIA/EIA-422, ISO 8482, and ANSI X3.277 (HVD SCSI Fast-20) Applications
- Common-Mode Bus Voltage Range
 7 V to 12 V
- ESD Protection on Bus Terminals Exceeds 12 kV
- Driver Output Current up to ±60 mA
- Thermal Shutdown Protection
- Driver Positive and Negative Current Limiting
- Power-Up, Power-Down Glitch-Free Operation
- Pin-Compatible With the SN75ALS170
- Available in Shrink Small-Outline Package

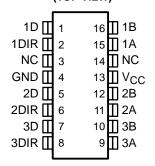
description

The SN65LBC170 and SN75LBC170 are monolithic integrated circuits designed for bidirectional data communication on multipoint bus-transmission lines. Potential applications include serial or parallel data transmission, cabled peripheral buses with twin axial, ribbon, or twisted-pair cabling. These devices are suitable for FAST-20 SCSI and can transmit or receive data pulses as short as 25 ns, with skew less than 3 ns.

These devices combine three 3-state differential line drivers and three differential input line receivers, all of which operate from a single 5-V power supply.

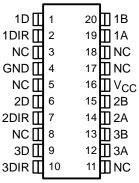
The driver differential outputs and the receiver differential inputs are connected internally to form three differential input/output (I/O) bus ports that are designed to offer minimum loading to the bus whenever the driver is disabled or $V_{CC} = 0$. These ports feature a wide common-mode voltage range making the device suitable for party-line applications over long cable runs.

SN65LBC170DB (marked as BL170) SN75LBC170DB (marked as BL170) (TOP VIEW)



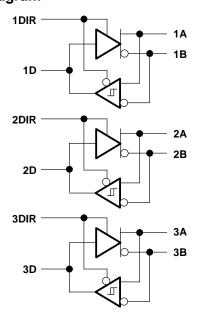
SN65LBC170DW (marked as 65LBC170) SN75LBC170DW (marked as 75LBC170)

(TOP VIEW)



NC - No internal connection

logic diagram





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

†The signaling rate of a line is the number of voltage transitions that are made per second expressed in the units bps (bits per second).



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description (continued)

The driver's active-high enable and the receiver's active-low enable are tied together internally and provide a direction input for each driver/receiver pair.

The SN75LBC170 is characterized for operation over the temperature range of 0°C to 70°C. The SN65LBC170 is characterized for operation over the temperature range of -40°C to 85°C.

AVAILABLE OPTIONS†

	PACKAGE				
TA	PLASTIC SHRINK SMALL-OUTLINE PLASTIC SMALL-OUTLINE (JEDEC MO-150) (JEDEC MS-013)				
0°C to 70°C	SN75LBC170DB	SN75LBC170DW			
-40°C to 85°C	SN65LBC170DB	SN65LBC170DW			

TAdd R suffix for taped and reel

Function Tables

EACH DRIVER

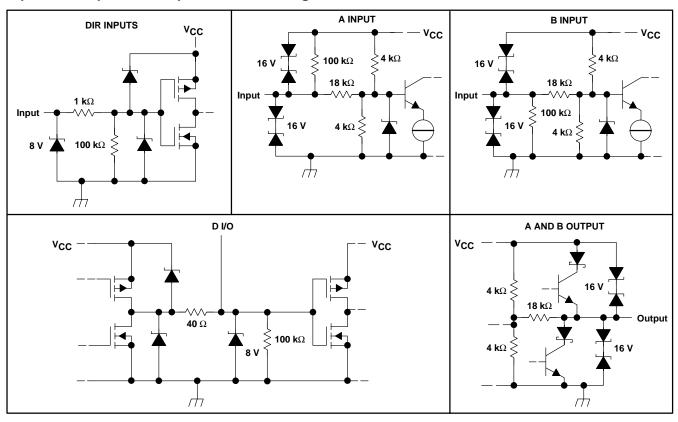
INPUT	ENABLE	OUTPUT	
D	DIR	Α	В
Н	Н	Н	Г
L	Н	L	Н
OPEN	Н	L	Н
Х	L	Z	Z
Χ	OPEN	Х	Χ

EACH RECEIVER

DIFFERENTIAL INPUT (VA-VB)	ENABLE DIR	OUTPUT D
$V_{ID} \ge 0.2 V$	L	Н
$-0.2 \text{ V} < \text{V}_{1D} < 0.2 \text{ V}$	L	?
$V_{ID} \le -0.2 V$	L	L
X	Н	Z
OPEN	L	Н

H = high level, L = low level, X = irrelevant, Z = high impedance (off), ? = indeterminate

equivalent input and output schematic diagrams





absolute maximum ratings†

Supply voltage, V _{CC} (see Note 1)	0.3 V to 6 V
Voltage range at any bus I/O terminal (steady state)	–10 V to 15 V
Voltage input range, A and B, (transient pulse through 100 Ω , see Figur	e 12)30 V to 30 V
Voltage range at any D or DIR terminal	-0.5 V to V _{CC} + 0.5 V
Electrostatic discharge: Human body model (A, B, GND) (see Note 2)	12 kV
All pins	5 kV
Charged-device model (all pins) (see Note 3).	1 kV
Continuous total power dissipation	See Power Dissipation Rating Table
Storage temperature range, T _{stq}	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential I/O bus voltages, are with respect to network ground terminal.
 - 2. Tested in accordance with JEDEC Standard 22, Test Method A114-A.
 - 3. Tested in accordance with JEDEC Standard 22, Test Method C101.

POWER DISSIPATION RATING TABLE

PACKAGE	$T_{\mbox{A}} \le 25^{\circ}\mbox{C}$ POWER RATING	DERATING FACTOR [‡] ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING
DB	995 mW	8.0 mW/°C	635 mW	515 mW
DW	1480 mW	11.8 mW/°C	950 mW	770 mW

[‡] This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}		4.75	5	5.25	V
Voltage at any bus I/O terminal	А, В	-7		12	V
High-level input voltage, VIH	D 010	2		VCC	.,
Low-level input voltage, V _{IL}	D, DIR	0		8.0	V
Differential input voltage, V _{ID}	A with respect to B	-12		12	V
	Driver	-60		60	
Output current	Receiver	-8		8	mA
Operating free-air temperature, T _A	SN75LBC170	0		70	20
	SN65LBC170	-40		85	°C

DRIVER SECTION

electrical characteristics over recommended operating conditions

PARAMETER		TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT			
VIK	Input clamp voltage	D and DIR	I _I = 18 mA		-1.5	-0.7		V		
٧o	Open-circuit output voltage (sir	ngle-ended)	A or B, No load		0		VCC	V		
		No load		3.8	4.3	VCC				
VOD(SS)	Steady-state differential output magnitude‡	voltage	$R_L = 54 \Omega$,	See Figure 1	1	1.6	2.4	V		
, ,	magnitude		With common-mode loading, See		1	1.6	2.4			
$\Delta V_{ extsf{OD}}$	Change in differential output vomagnitude, V _{OD(H)} - V _{OD}		_		-0.2		0.2	V		
V _{OC(SS)}	Steady-state common-mode	output voltage	$R_L = 54 \Omega$, $C_L = 50 pF$	See Figure 1	2	2.4	2.8			
ΔV _{OC} (SS)	Change in steady-state common voltage (VOC(H) - VOC(L))	on-mode output	CL = 50 pr	- Ο <u>Γ</u> = 30 βι	ο <u>ι</u> - σο μ.		-0.2		0.2	V
lį	Input current		D, DIR		-100		100	μΑ		
lo	Output current with power off		$V_{CC} = 0 V$,	$V_0 = -7 \text{ V to } 12 \text{ V}$	-700		900	μΑ		
los	Short-circuit output current		$V_0 = -7 \text{ V to } 12 \text{ V},$	See Figure 7	-250		250	mA		
ICC	Supply current (driver enable	d)	D at 0 V or V _{CC} ,	DIR at V _{CC} , No load		14	20	mA		

[†] All typical values are at $V_{CC} = 5 \text{ V}$ and $T_A = 25^{\circ}\text{C}$.

switching characteristics over recommended operating conditions

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
^t PLH	Differential output propagation delay, low-to high		4	8.5	12	
^t PHL	Differential output propagation delay, high-to-low		4	8.5	11	
t _r	Differential output rise time		3	7.5	11	
t _f	Differential output fall time	$R_L = 54 \Omega$, $C_L = 50 pF$, See Figure 3	3	7.5	11	ns
t _{sk(p)}	Pulse skew (tpLH – tpHL)				2	
t _{sk(o)}	Output skew§				1.5	
tsk(pp)	Part-to-part skew¶				2	
^t PLH	Differential output propagation delay, low-to high	-	3	7	10	
^t PHL	Differential output propagation delay, high-to-low		3	7.5	10	
t _r	Differential output rise time	0 5'	3	7.5	12	
t _f	Differential output fall time	See Figure 4, (HVD SCSI double-terminated load)	3	7.5	12	ns
t _{sk(p)}	Pulse skew (tpLH – tpHL)	(TVB GGGT double toffilliated load)			3	
tsk(o)	Output skew§				1.5	
tsk(pp)	Part-to-part skew¶				2.5	
^t PZH	Output enable time to high level	See Figure 5		15	25	
^t PHZ	Output disable time from high level			18	25	ns
^t PZL	Output enable time to low level	0 5'		10	25	
^t PLZ	Output disable time from low level	See Figure 6		17	25	ns

[§] Output skew $(t_{sk(0)})$ is the magnitude of the time delay difference between the outputs of a single device with all of the inputs connected together. ¶ Part-to-part skew $(t_{sk(pp)})$ is the magnitude of the difference in propagation delay times between any specified terminals of two devices when both devices operate with the same input signals, the same supply voltages, at the same temperature, and have identical packages and test circuits.



[‡] The minimum VOD may not fully comply with TIA/EIA-485-A at operating temperatures below 0°C. System designers should take the possibly lower output signal into account in determining the maximum signal-transmission distance.

RECEIVER SECTION

electrical characteristics over recommended operating conditions

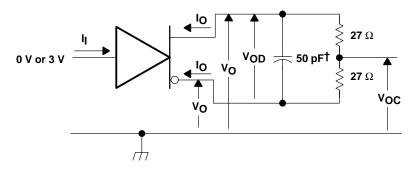
PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V _{IT+}	Positive-going differential input voltage threshold					0.2	
V _{IT} _	Negative-going differential input voltage threshold	See Figure 8	See Figure 8				V
V _{hys}	Hysteresis voltage (V _{IT+} – V _{IT-})	1			40		mV
Vон	High-level output voltage	V _{ID} = 200 mV, I _{OH} = -8 mA, See Figure 8		4	4.7	VCC	.,
VOL	Low-level output voltage	V_{ID} = -200 mV, I_{OL} = -8 mA, See Figure 8		0	0.2	0.4	V
	Line in the second of the seco	Other leaves 0.1/	V _I = 12 V			0.9	4
Ч	Line input current	Other input = 0 V	V _I = −7 V	-0.7			mA
R _I	Input resistance	A, B		12			kΩ
ICC	Supply current (receiver enabled)	A, B, D, and DIR oper	1			16	mA

[†] All typical values are at $V_{CC} = 5 \text{ V}$ and $T_A = 25^{\circ}\text{C}$.

switching characteristics over recommended operating conditions

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
^t PLH	Propagation delay time, low-to-high level output		7		16	ns
t _{PHL}	Propagation delay time, high-to-low level output	See Figure 9	7		16	ns
t _r	Receiver output rise time			1.3	3	ns
t _f	Receiver output fall time			1.3	3	ns
^t PZH	Receiver output enable time to high level	0 5 40		26	40	
^t PHZ	Receiver output disable time from high level	See Figure 10			40	ns
t _{PZL}	Receiver output enable time to low level	0 5 44		29	40	
^t PLZ	Receiver output enable time to high level	See Figure 11			40	ns
t _{sk(p)}	Pulse skew (tpLH - tpHL)				2	ns
t _{sk(o)}	Output skew [‡]				1.5	ns
t _{sk(pp)}	Part-to-part skew§				3	ns

[‡] Output skew (t_{sk(o)}) is the magnitude of the time delay difference between the outputs of a single device with all of the inputs connected together. § Part-to-part skew (t_{sk(pp)}) is the magnitude of the difference in propagation delay times between any specified terminals of two devices when both devices operate with the same input signals, the same supply voltages, at the same temperature, and have identical packages and test circuits.



† Includes probe and jig capacitance

Figure 1. Driver Test Circuit, $V_{\mbox{\scriptsize OD}}$ and $V_{\mbox{\scriptsize OC}}$ Without Common-Mode Loading

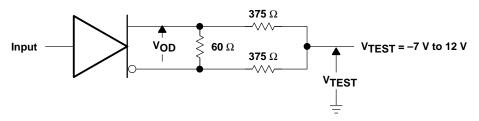


Figure 2. Driver Test Circuit, V_{OD} With Common-Mode Loading

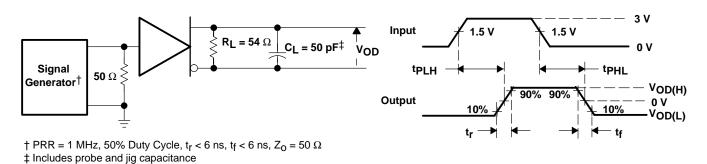
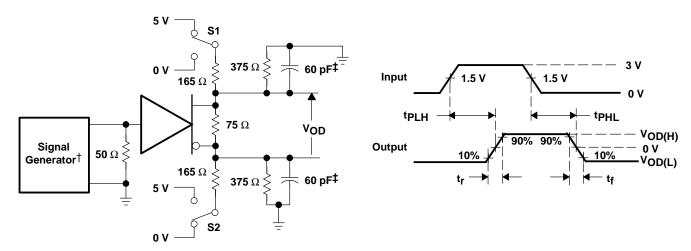
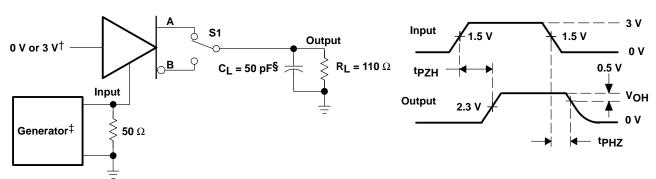


Figure 3. Driver Switching Test Circuit and Waveforms, 485-Loading



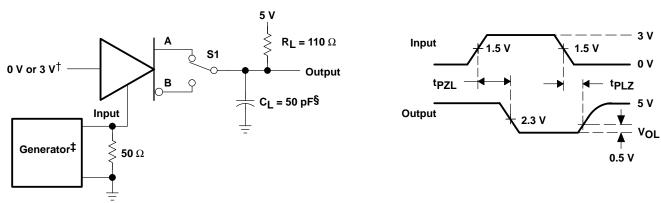
- † PRR = 1 MHz, 50% Duty Cycle, t_{f} < 6 ns, t_{f} < 6 ns, Z_{O} = 50 Ω
- ‡ Includes probe and jig capacitance

Figure 4. Driver Switching Test Circuit and Waveforms, HVD SCSI-Loading (double terminated)



- † 3 V if testing A output, 0 V if testing B output
- ‡ PRR = 1 MHz, 50% Duty Cycle, t_r < 6 ns, t_f < 6 ns, Z_0 = 50 Ω
- § Includes probe and jig capacitance

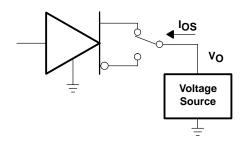
Figure 5. Driver Enable/Disable Test, High Output



- † 0 V if testing A output, 3 V if testing B output
- \ddagger PRR = 1 MHz, 50% Duty Cycle, t_{f} < 6 ns, t_{f} < 6 ns, Z_{O} = 50 Ω
- § Includes probe and jig capacitance

Figure 6. Driver Enable/Disable Test, Low Output

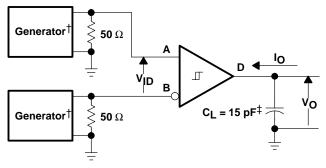


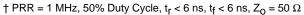


V_{ID} V_O

Figure 7. Driver Short-Circuit Test

Figure 8. Receiver DC Parameters





‡ Includes probe and jig capacitance

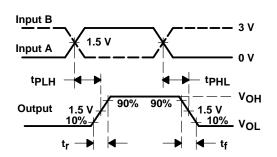
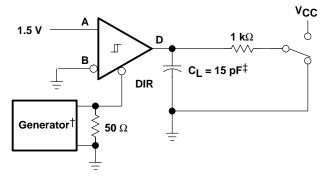
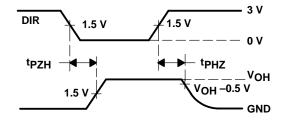


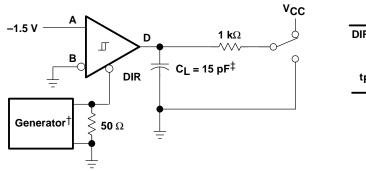
Figure 9. Receiver Switching Test Circuit and Waveforms

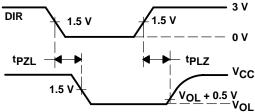




- † PRR = 1 MHz, 50% Duty Cycle, t_{f} < 6 ns, t_{f} < 6 ns, Z_{O} = 50 Ω
- ‡ Includes probe and jig capacitance

Figure 10. Receiver Enable/Disable Test, High Output





- † PRR = 1 MHz, 50% Duty Cycle, $t_{\rm f}$ < 6 ns, $t_{\rm f}$ < 6 ns, $Z_{\rm O}$ = 50 Ω
- ‡ Includes probe and jig capacitance

Figure 11. Receiver Enable/Disable Test, Low Output

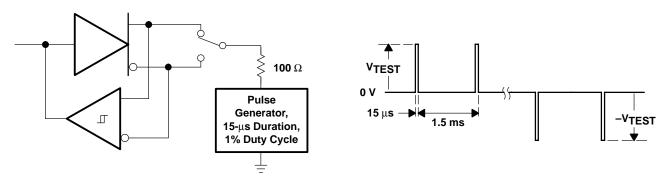
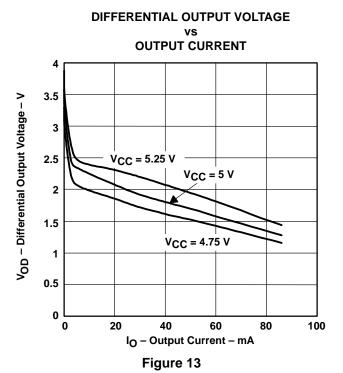
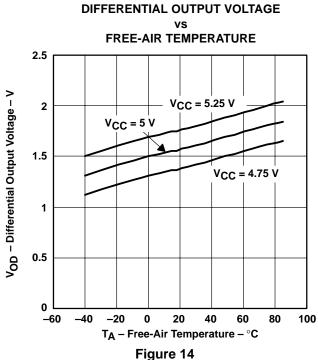
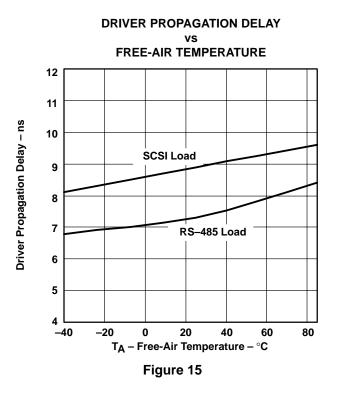
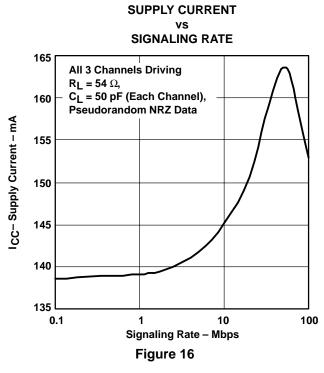


Figure 12. Test Circuit and Waveform, Transient Over Voltage Test









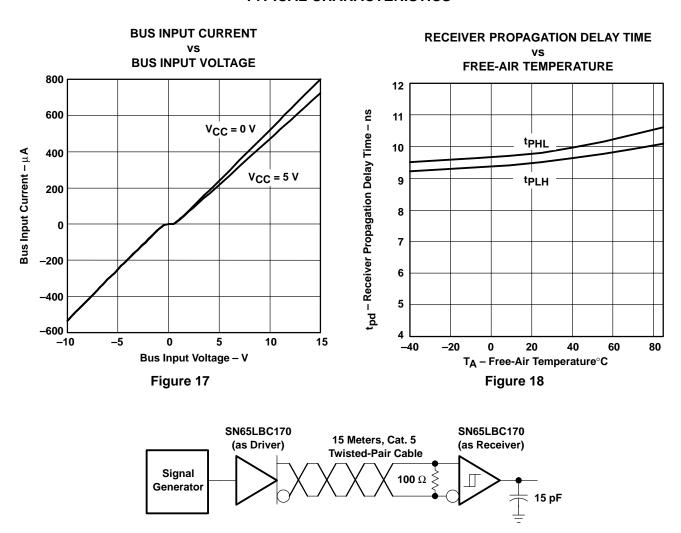


Figure 19. Circuit Diagram for Signaling Characteristics

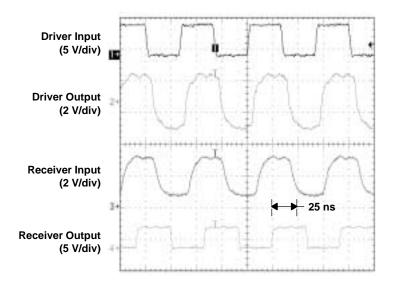


Figure 20. Signal Waveforms at 30 Mbps

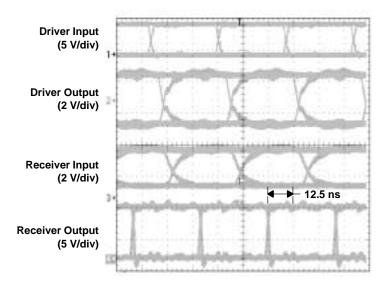


Figure 21. Eye Patterns, Pseudorandom Data at 30 Mbps

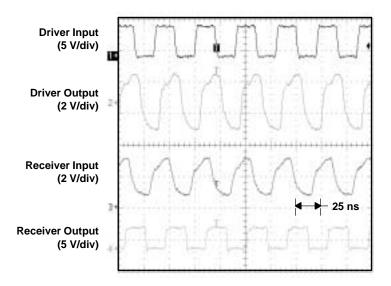


Figure 22. Signal Waveforms at 50 Mbps

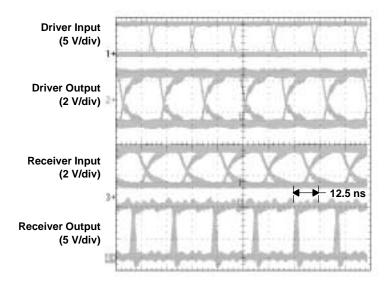


Figure 23. Eye Patterns, Pseudorandom Data at 50 Mbps

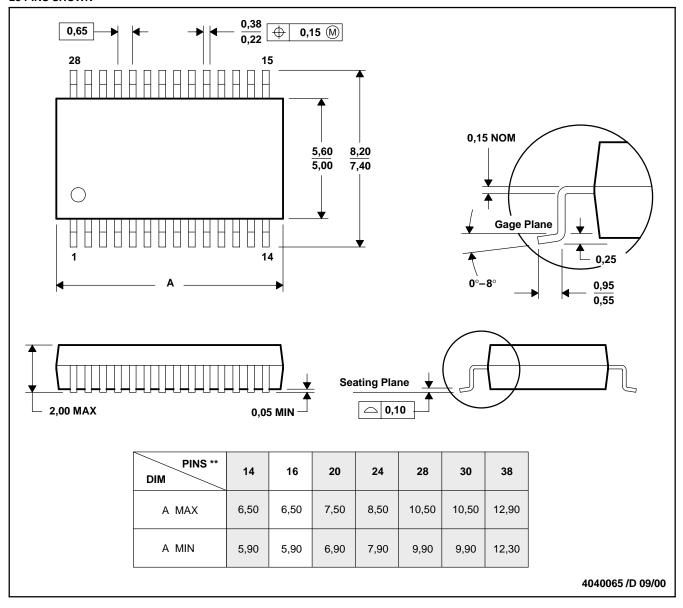
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MECHANICAL DATA

DB (R-PDSO-G**)

28 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

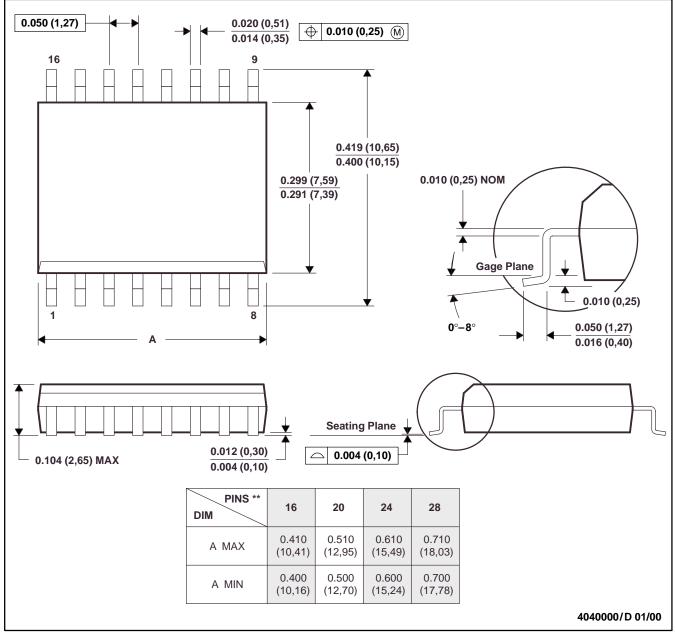
D. Falls within JEDEC MO-150

MECHANICAL DATA

DW (R-PDSO-G**)

16 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013



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